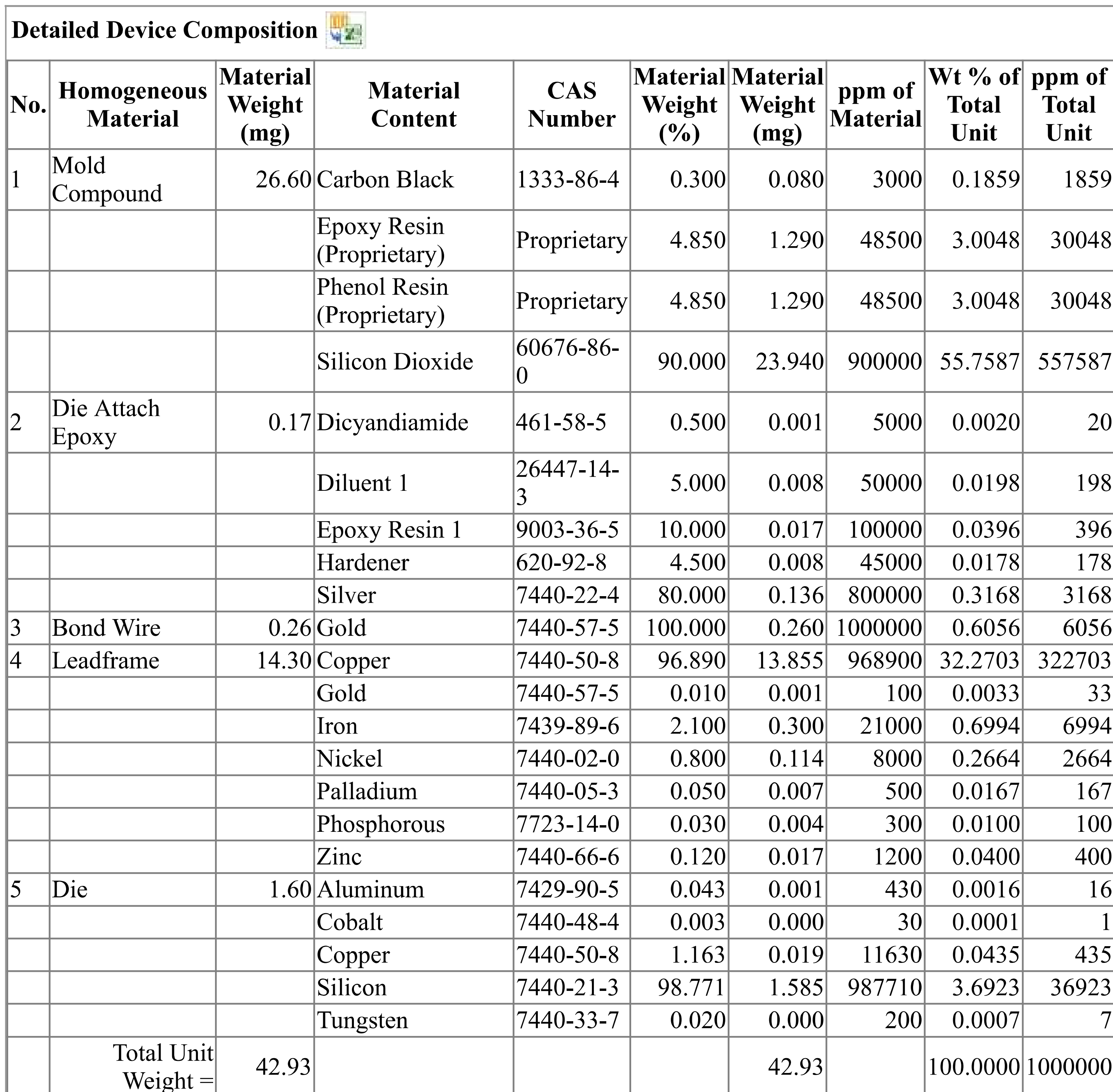
Date: 4/13/2021
Material Number: SI5351B-B04514-GM
Pkg Config.: PK0951



Detailed Device Composition

No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Mold Compound	26.60	Carbon Black	1333-86-4	0.300	0.080	3000	0.1859	1859
			Epoxy Resin (Proprietary)	Proprietary	4.850	1.290	48500	3.0048	30048
			Phenol Resin (Proprietary)	Proprietary	4.850	1.290	48500	3.0048	30048
			Silicon Dioxide	60676-86-0	90.000	23.940	900000	55.7587	557587
2	Die Attach Epoxy	0.17	Dicyandiamide	461-58-5	0.500	0.001	5000	0.0020	20
			Diluent 1	26447-14-3	5.000	0.008	50000	0.0198	198
			Epoxy Resin 1	9003-36-5	10.000	0.017	100000	0.0396	396
			Hardener	620-92-8	4.500	0.008	45000	0.0178	178
			Silver	7440-22-4	80.000	0.136	800000	0.3168	3168
3	Bond Wire	0.26	Gold	7440-57-5	100.000	0.260	1000000	0.6056	6056
4	Leadframe	14.30	Copper	7440-50-8	96.890	13.855	968900	32.2703	322703
			Gold	7440-57-5	0.010	0.001	100	0.0033	33
			Iron	7439-89-6	2.100	0.300	21000	0.6994	6994
			Nickel	7440-02-0	0.800	0.114	8000	0.2664	2664
			Palladium	7440-05-3	0.050	0.007	500	0.0167	167
			Phosphorous	7723-14-0	0.030	0.004	300	0.0100	100
			Zinc	7440-66-6	0.120	0.017	1200	0.0400	400
5	Die	1.60	Aluminum	7429-90-5	0.043	0.001	430	0.0016	16
			Cobalt	7440-48-4	0.003	0.000	30	0.0001	1
			Copper	7440-50-8	1.163	0.019	11630	0.0435	435
			Silicon	7440-21-3	98.771	1.585	987710	3.6923	36923
			Tungsten	7440-33-7	0.020	0.000	200	0.0007	7
	Total Unit Weight =	42.93				42.93		100.0000	1000000